

Customer No.: 31561
Application No.: 10/605,660
Docket No.: 10041-US-PA

AMENDMENTS

FOR THE CLAIMS

Claims 1-10. Cancelled.

Claim 11 (original) A high density semiconductor package, comprising:
a substrate, having a surface;
a first package module, being disposed on the surface of the substrate; and
a plurality of second package modules, being disposed on the surface of the substrate surrounding the first package module, wherein a corner of each of the second package modules face a side of the first package module.

Claim 12 (original) The high density semiconductor package as claimed in claim 11, wherein a gap width between the second package module and the first package module is larger than 2 mm.

Claim 13 (original) The high density semiconductor package structure as claimed in claim 11, wherein the first package module is arranged coplanar with the second package modules.

Claim 14 (original) The high density semiconductor package as claimed in claim 11, wherein the first package module comprises:

- a chip;
- a plurality of bumps located between the chip and the substrate; and
- an underfill located between the chip and the substrate and enveloping the bumps.

Claim 15 (original) The high density semiconductor package as claimed in claim 11, wherein each of the second package modules comprises:

- a chip;
- a plurality of bumps located between the chip and the substrate; and
- an underfill located between the chip and the substrate and enveloping the bumps.

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Claims 16-23. Cancelled.

Claim 24 (New) The high density semiconductor package as claimed in claim 11, wherein the first package module is arranged substantially orthogonal to the second package modules.

Claim 25 (New) The high density semiconductor package as claimed in claim 11, wherein the first package module is arranged substantially non-orthogonal to the second package module.